

Siliconix

### N-Channel Enhancement-Mode Transistor

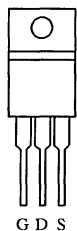
175°C Maximum Junction Temperature

#### Product Summary

$V_{DS}$ (V)	$r_{DS(on)}$ ( $\Omega$ )	$I_D$ (A)
60	0.014	60

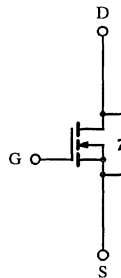
See lower-cost version: SUP60N06-14

TO-220AB



Top View

DRAIN connected to TAB



N-Channel MOSFET

#### Absolute Maximum Ratings ( $T_C = 25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current ( $T_J = 150^\circ\text{C}$ )	$I_D$	$T_C = 25^\circ\text{C}$	A
		$T_C = 100^\circ\text{C}$	
Pulsed Drain Current	$I_{DM}$	240	W
Avalanche Current <sup>a</sup>	$I_{AR}$	60	
Repetitive Avalanche Energy	$L = 0.1$ mH $E_{AR}$	180	
Power Dissipation	$P_D$	$T_C = 25^\circ\text{C}$	150
		$T_C = 100^\circ\text{C}$	75
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to 175	$^\circ\text{C}$
Lead Temperature (1/16" from case for 10 sec.)	$T_L$	300	

#### Thermal Resistance Ratings

Parameter	Symbol	Typical	Maximum	Unit
Junction-to-Ambient	$R_{thJA}$		80	$^\circ\text{C}/\text{W}$
Junction-to-Case	$R_{thJC}$		1.0	
Case-to-Sink	$R_{thCS}$	1.0		

Notes:

a. Duty cycle  $\leq 1\%$

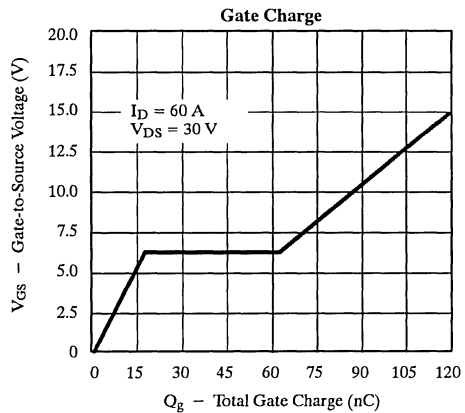
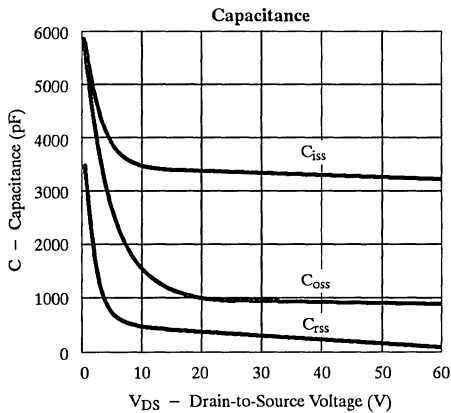
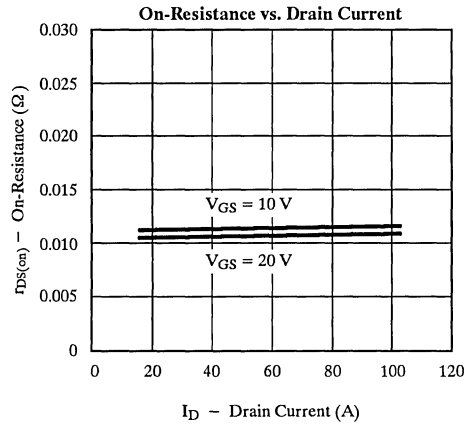
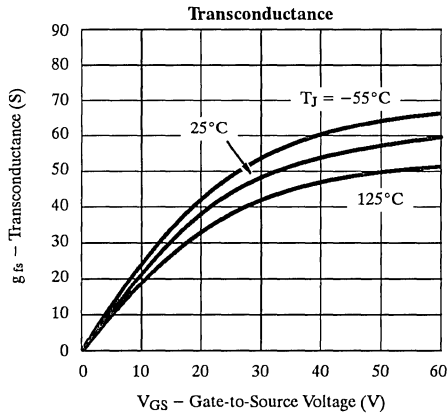
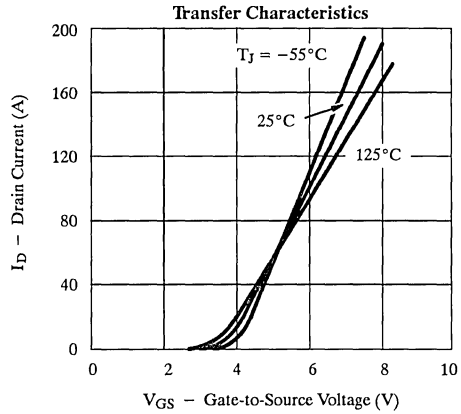
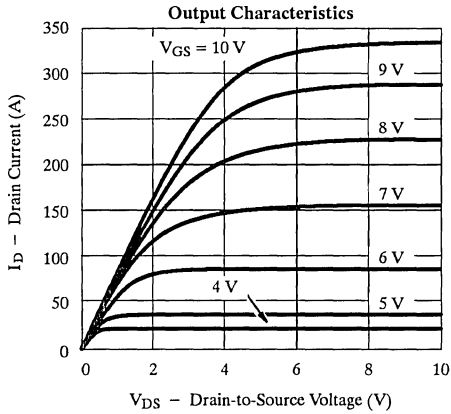
### Specifications ( $T_J = 25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Min	Typ <sup>a</sup>	Max	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	60			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{DS} = 1\text{ mA}$	2.0	3.0	4.0	
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$			$\pm 500$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 48\text{ V}, V_{GS} = 0\text{ V}$			25	$\mu\text{A}$
		$V_{DS} = 48\text{ V}, V_{GS} = 0\text{ V}, T_J = 125^\circ\text{C}$			250	
		$V_{DS} = 48\text{ V}, V_{GS} = 0\text{ V}, T_J = 175^\circ\text{C}$			500	
On-State Drain Current <sup>b</sup>	$I_{D(on)}$	$V_{DS} = 10\text{ V}, V_{GS} = 10\text{ V}$	60			A
Drain-Source On-State Resistance <sup>b</sup>	$r_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 30\text{ A}$		0.012	0.014	$\Omega$
		$V_{GS} = 10\text{ V}, I_D = 30\text{ A}, T_J = 125^\circ\text{C}$		0.020	0.023	
		$V_{GS} = 10\text{ V}, I_D = 30\text{ A}, T_J = 175^\circ\text{C}$		0.025	0.028	
Forward Transconductance <sup>b</sup>	$g_{fs}$	$V_{DS} = 15\text{ V}, I_D = 30\text{ A}$	30	48		S
<b>Dynamic</b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$		3450		$\text{pF}$
Output Capacitance	$C_{oss}$			1000		
Reverse Transfer Capacitance	$C_{rss}$			230		
Total Gate Charge <sup>c</sup>	$Q_g$	$V_{DS} = 30\text{ V}, V_{GS} = 10\text{ V}, I_D = 60\text{ A}$		95	130	$\text{nC}$
Gate-Source Charge <sup>c</sup>	$Q_{gs}$			20		
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			45		
Turn-On Delay Time <sup>c</sup>	$t_{d(on)}$	$V_{DD} = 30\text{ V}, R_L = 0.47\ \Omega$ $I_D = 60\text{ A}, V_{GEN} = 10\text{ V}, R_G = 2.5\ \Omega$		15	30	$\text{ns}$
Rise Time <sup>c</sup>	$t_r$			130	180	
Turn-Off Delay Time <sup>c</sup>	$t_{d(off)}$			50	100	
Fall Time <sup>c</sup>	$t_f$			20	50	
<b>Source-Drain Diode Ratings and Characteristics (<math>T_C = 25^\circ\text{C}</math>)</b>						
Continuous Current	$I_s$				60	A
Pulsed Current	$I_{SM}$				240	
Forward Voltage <sup>b</sup>	$V_{SD}$	$I_F = 60\text{ A}, V_{GS} = 0\text{ V}$		1.0	1.8	V
Reverse Recovery Time	$t_{rr}$	$I_F = 60\text{ A}, dI_F/dt = 100\text{ A}/\mu\text{s}$		130	200	ns
Peak Reverse Recovery Current	$I_{RM(REC)}$			9		A
Reverse Recovery Charge	$Q_{rr}$			0.6		$\mu\text{C}$

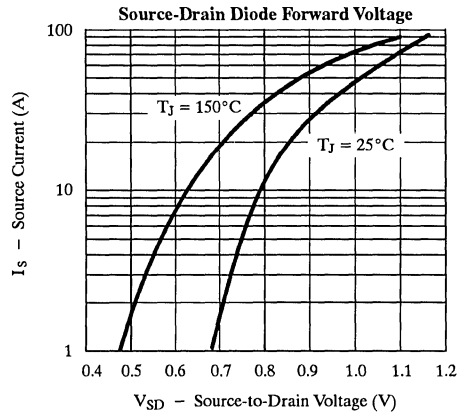
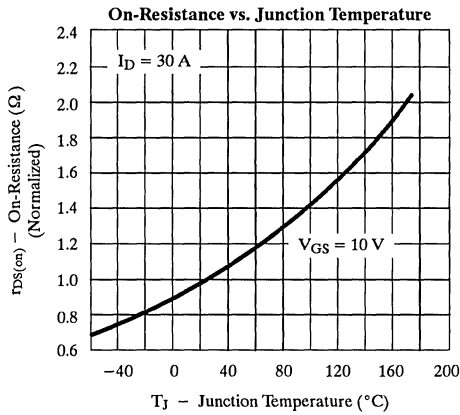
**Notes:**

- For design aid only; not subject to production testing.
- Pulse test; pulse width  $\leq 300\ \mu\text{s}$ , duty cycle  $\leq 2\%$ .
- Independent of operating temperature.

### Typical Characteristics (25°C Unless Otherwise Noted)



### Typical Characteristics (25°C Unless Otherwise Noted)



### Thermal Ratings

